

Replacement Drawings

This exploded perspective view illustrates the assembly of a multi-layered electronic device. The components are arranged vertically as follows:

- 700**: A square frame or bezel at the top.
- 100**: A top layer assembly including a substrate **140**, a patterned layer **135**, and a conductive layer **130** with a series of rectangular openings.
- 110**: A middle layer assembly including a substrate **111** and a conductive layer **112**.
- 400**: A layer assembly including a substrate **430** and a conductive layer **420**.
- 240**: A layer assembly including a substrate **440** and a conductive layer **410**.
- 500**: A bottom layer assembly including a substrate **230**, a conductive layer **310**, and a base layer **300**.
- 250**: A bottom-most layer assembly including a substrate **320** and a conductive layer **340**.
- 210** and **220**: A series of parallel conductive traces or pins extending from the bottom layer assembly.

FIG. 2

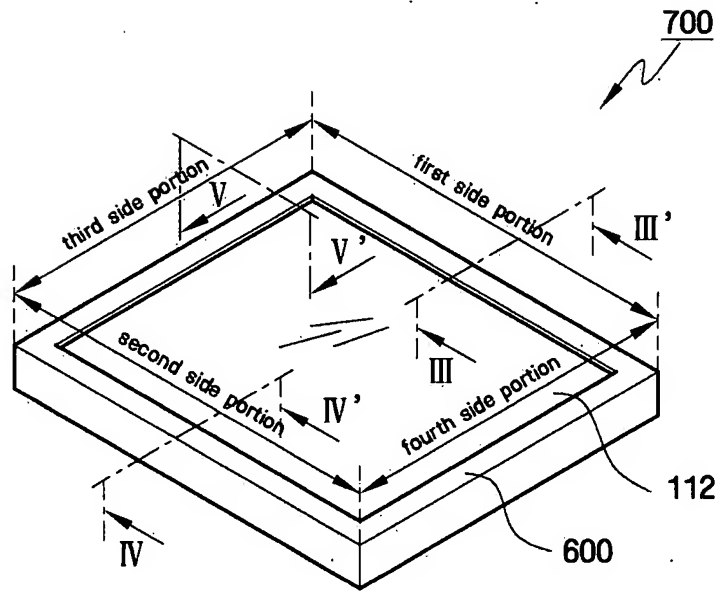


FIG. 3

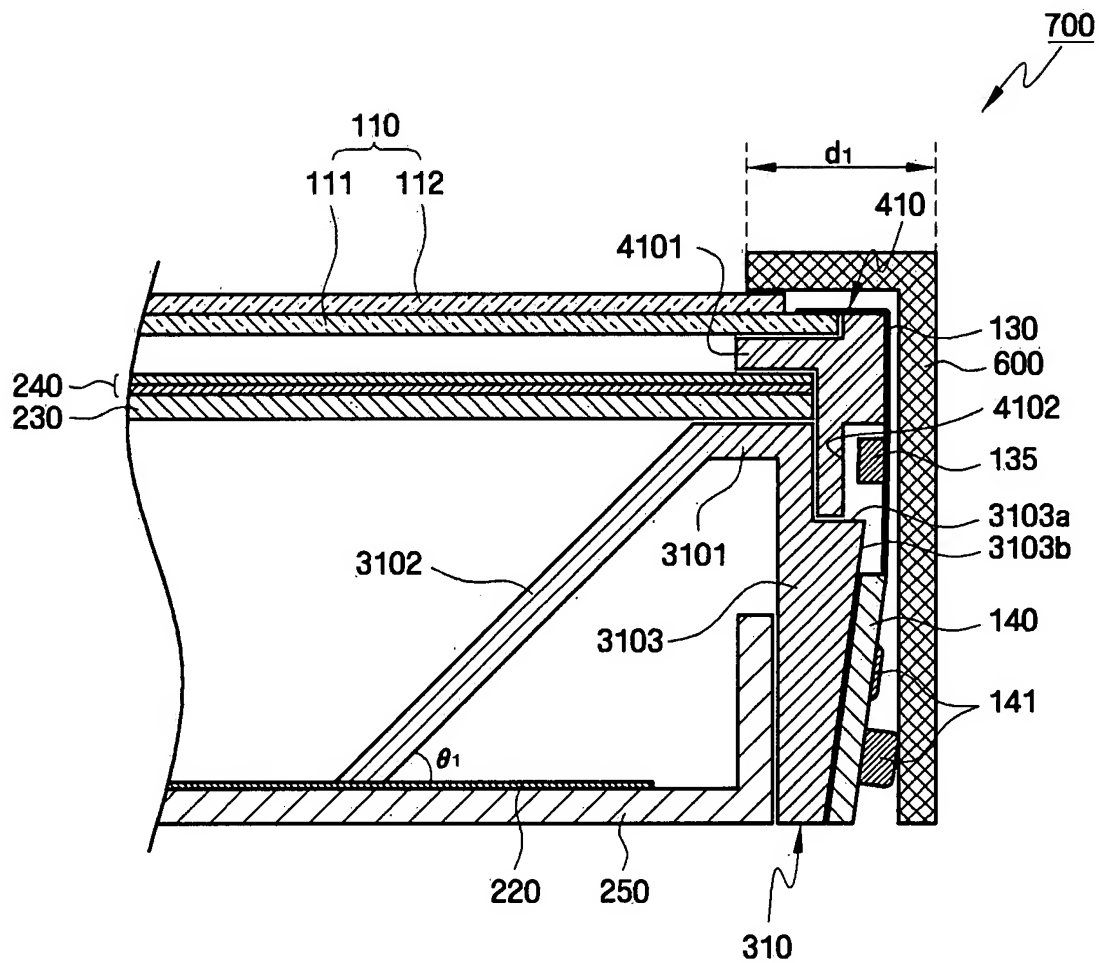


FIG. 4

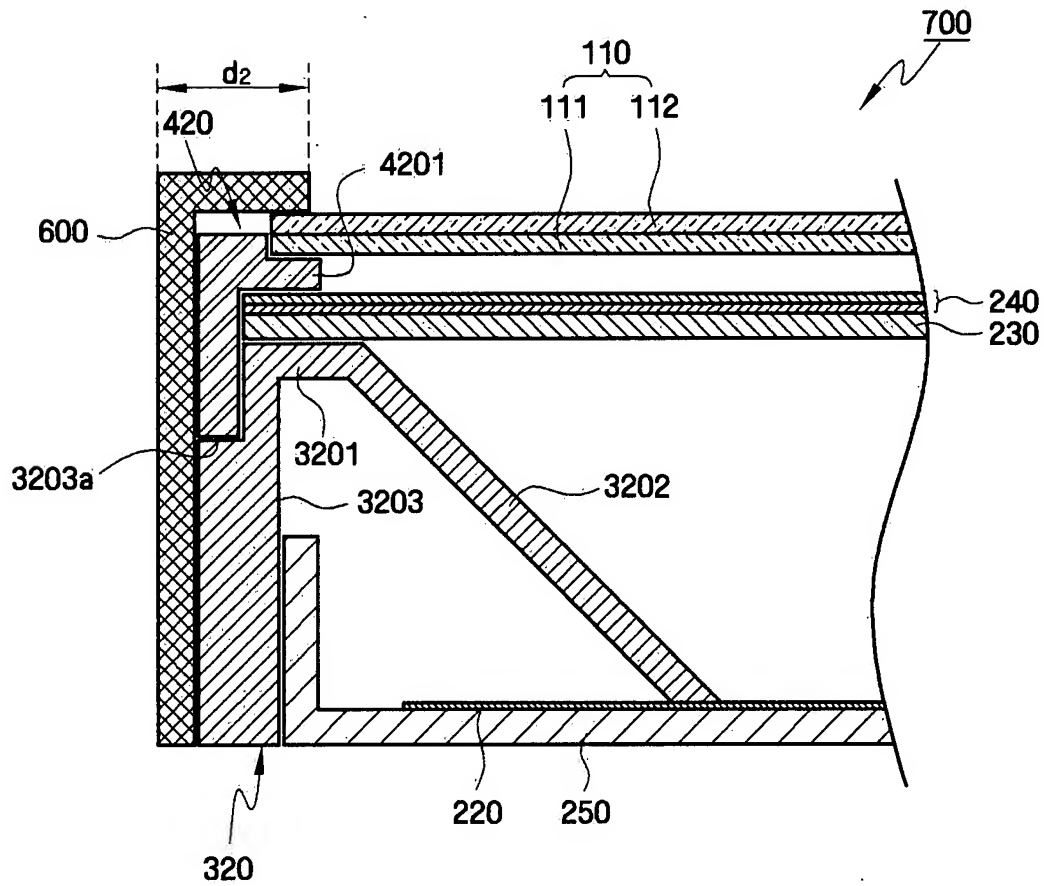
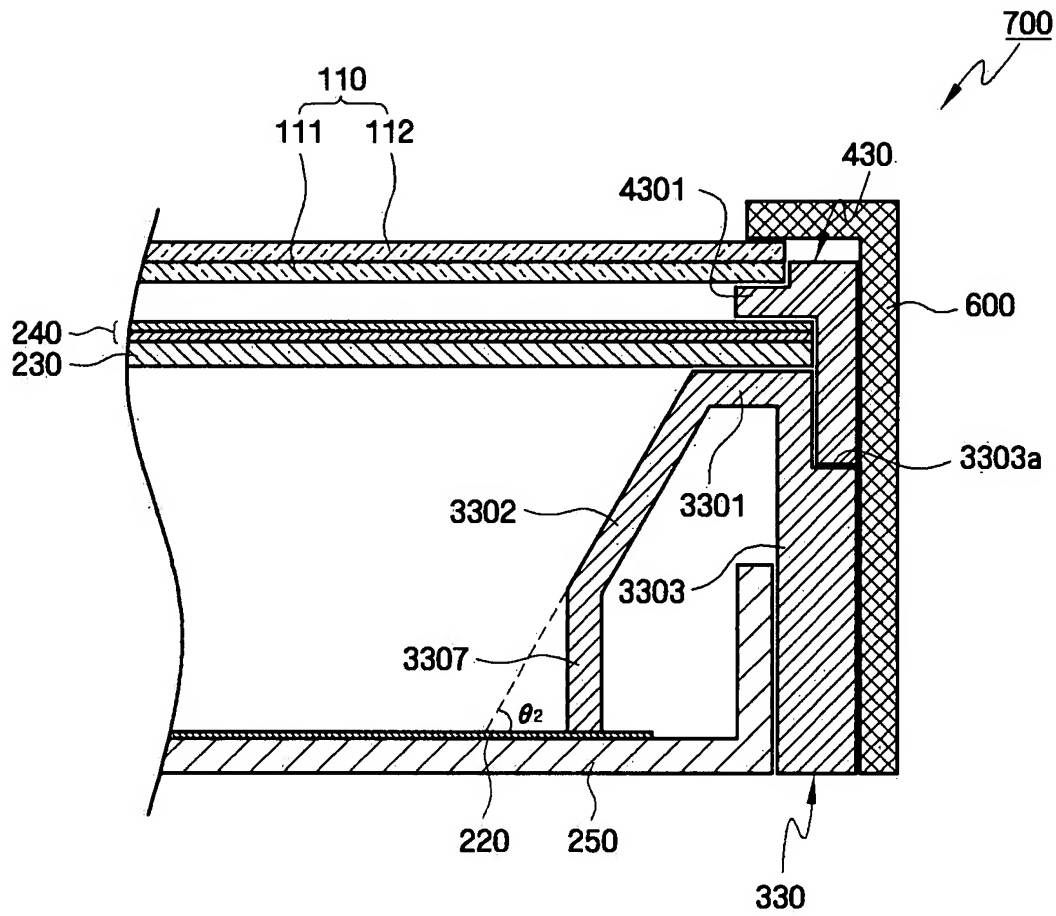
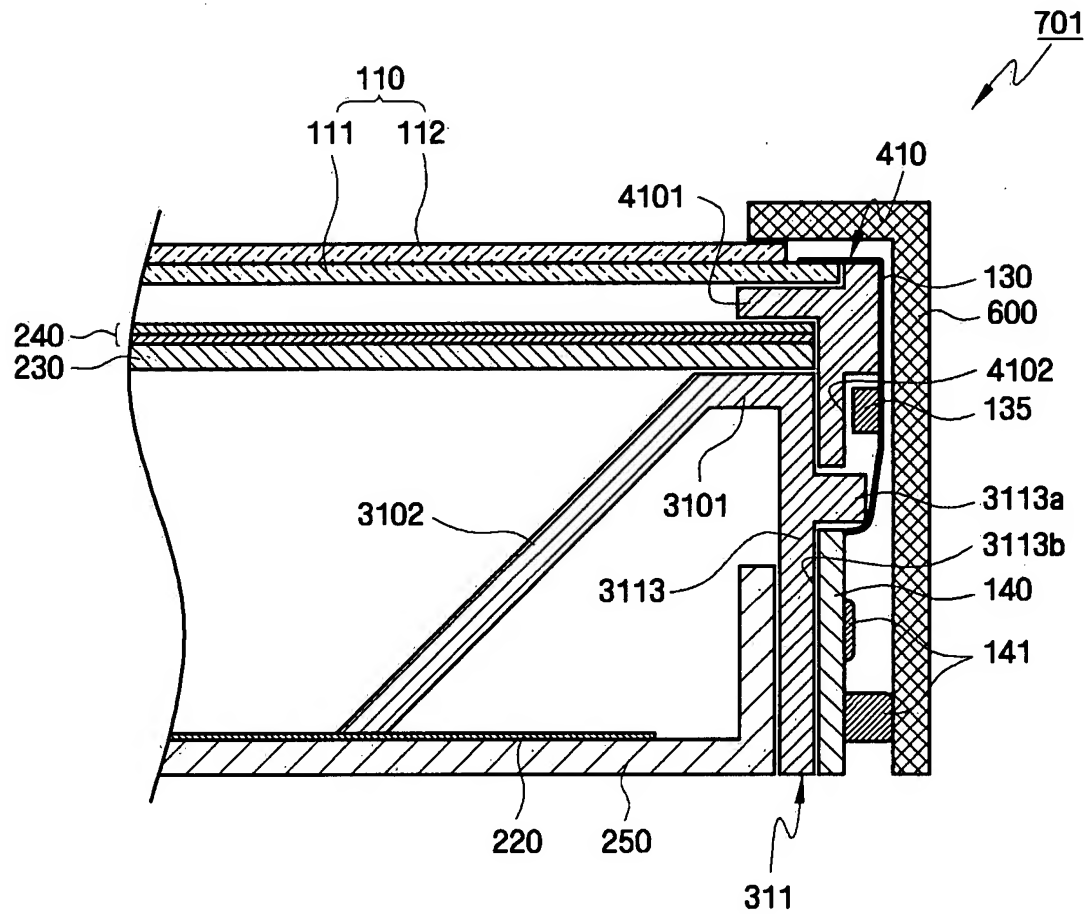


FIG. 5





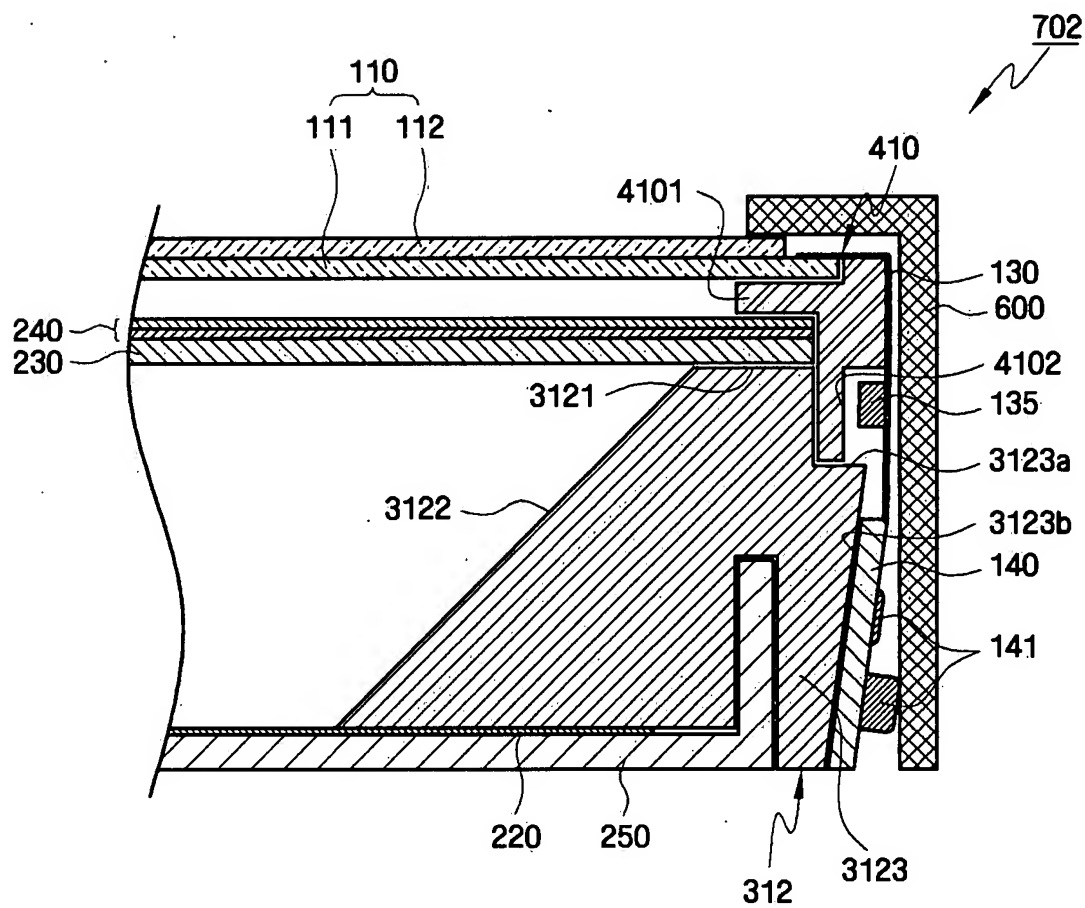


FIG. 8

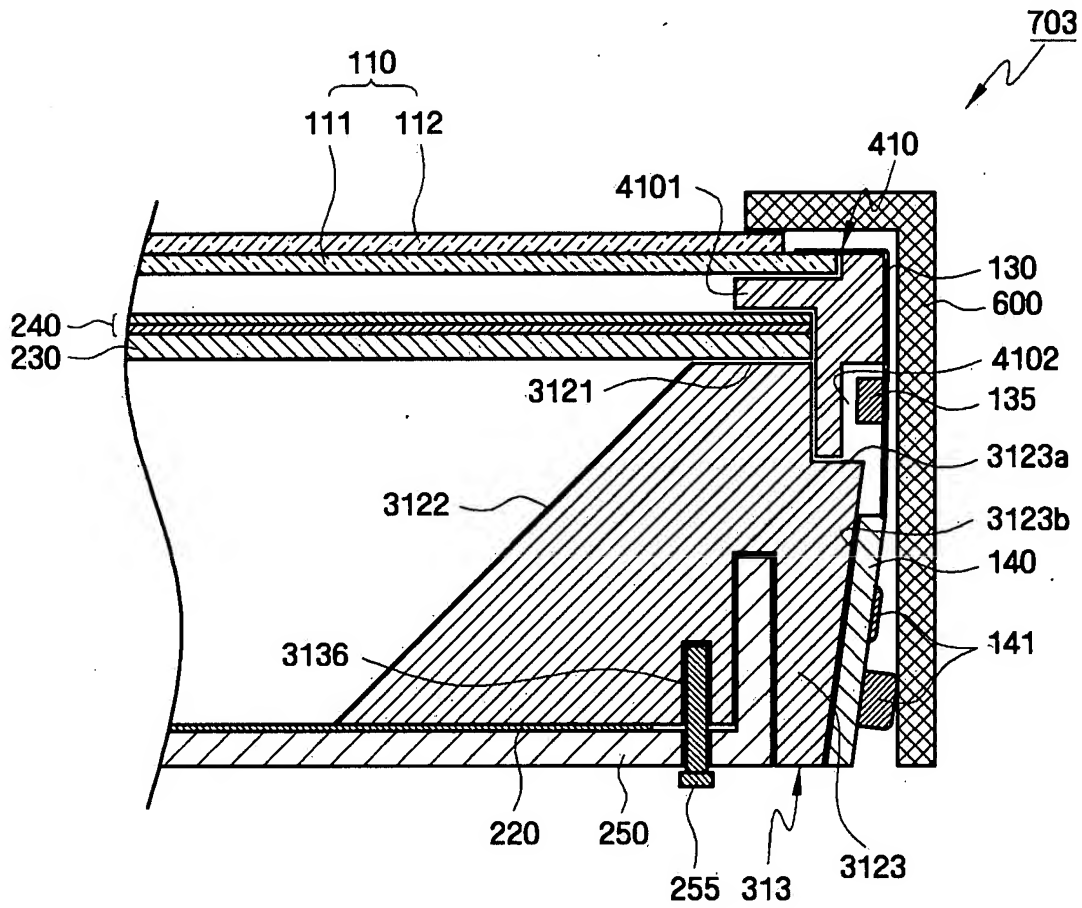


FIG. 9

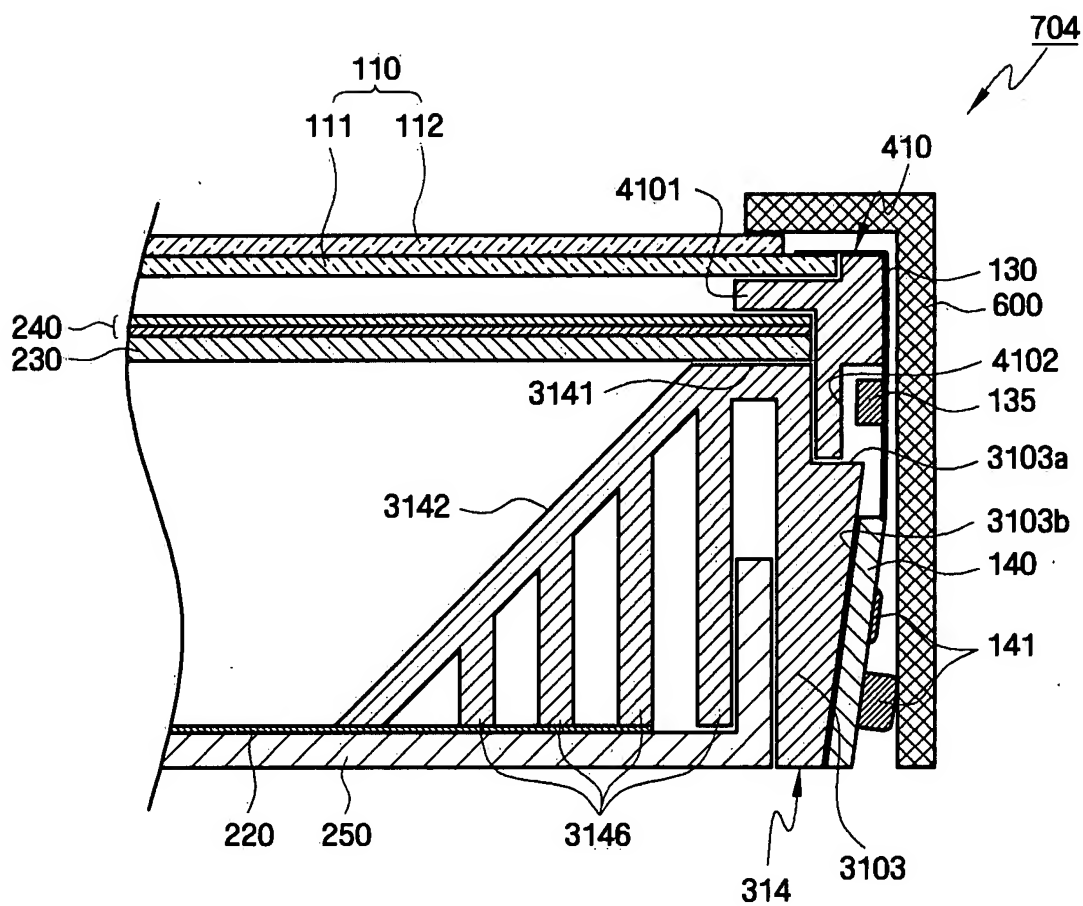


FIG. 10

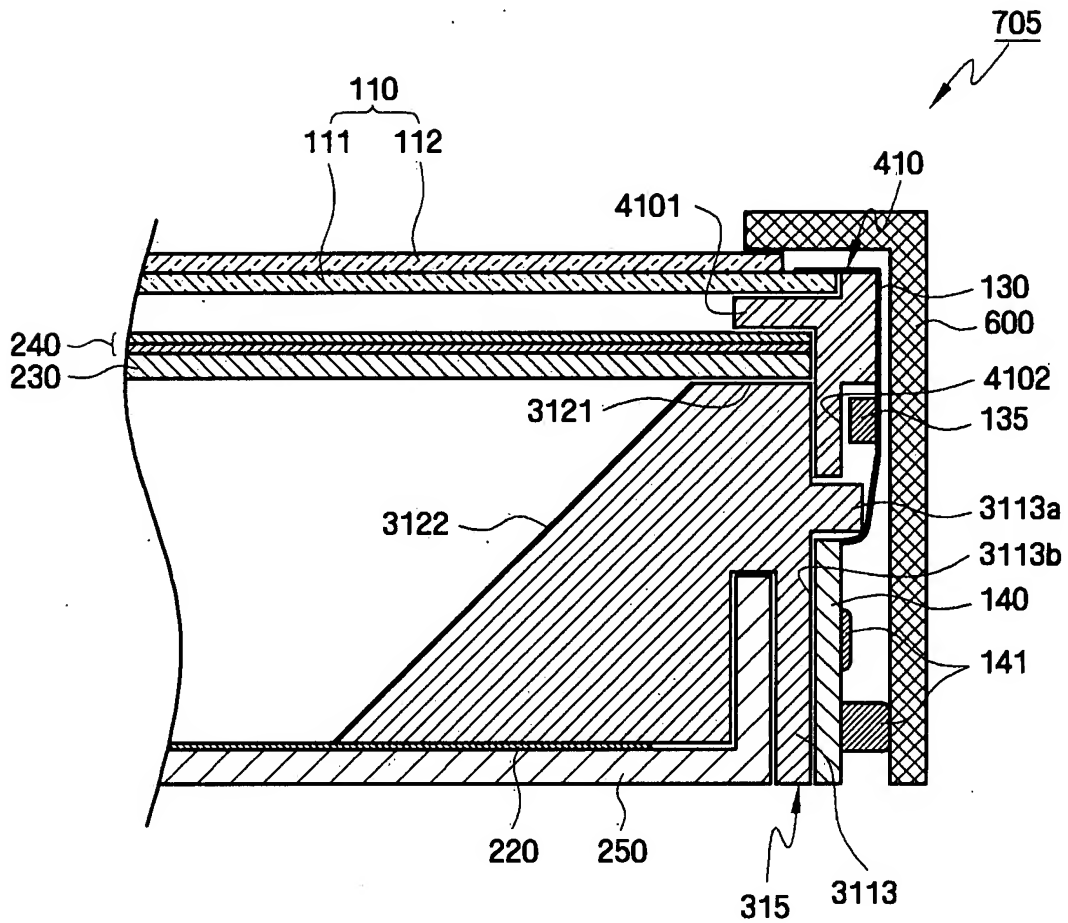


FIG. 11

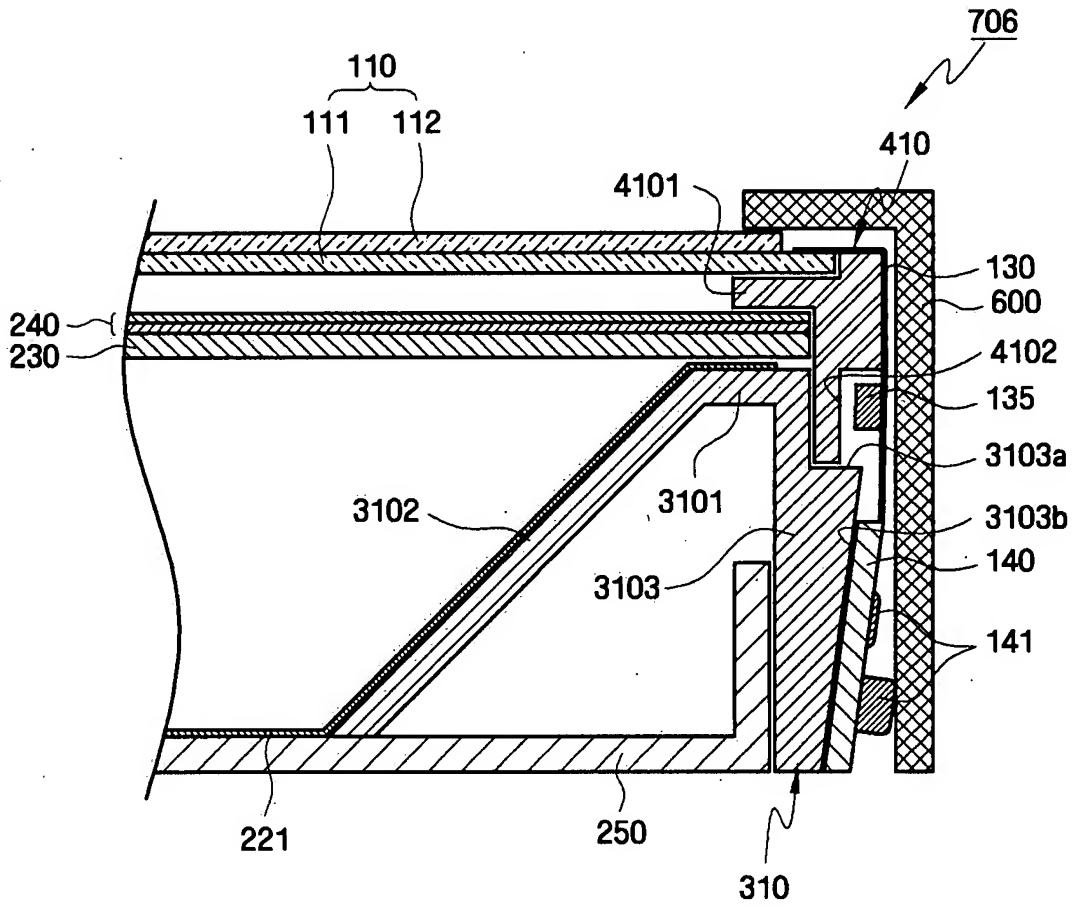


FIG. 12

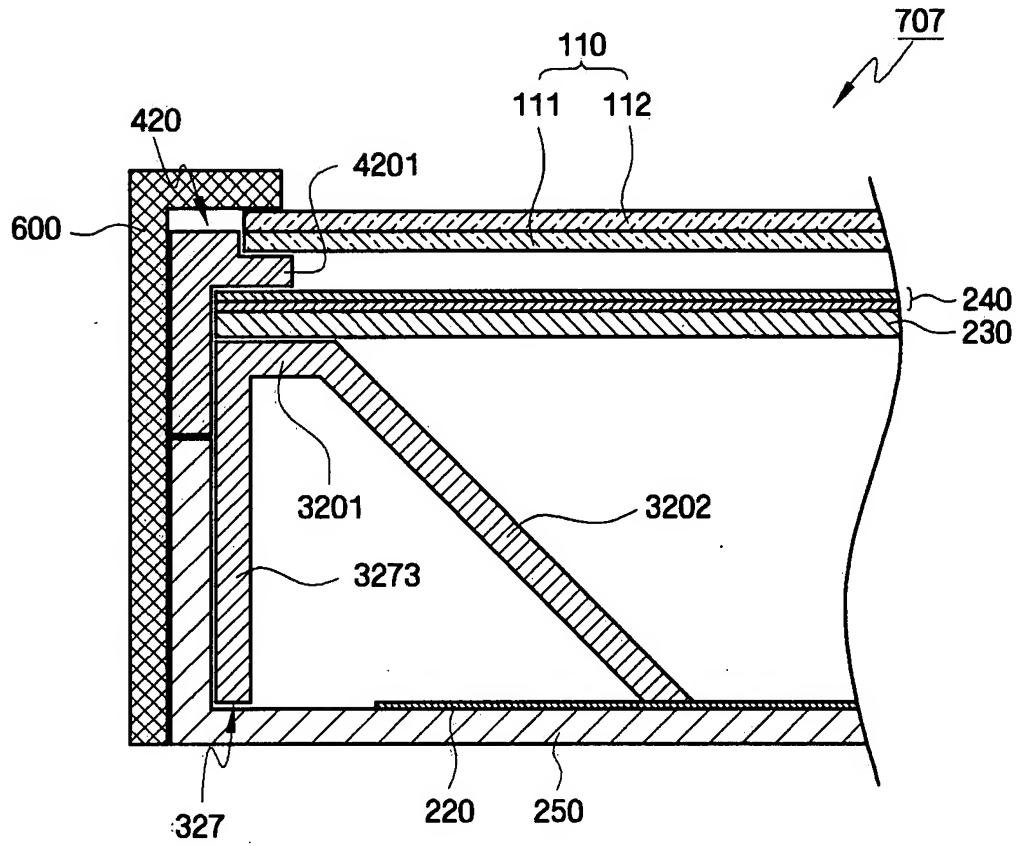


FIG. 13

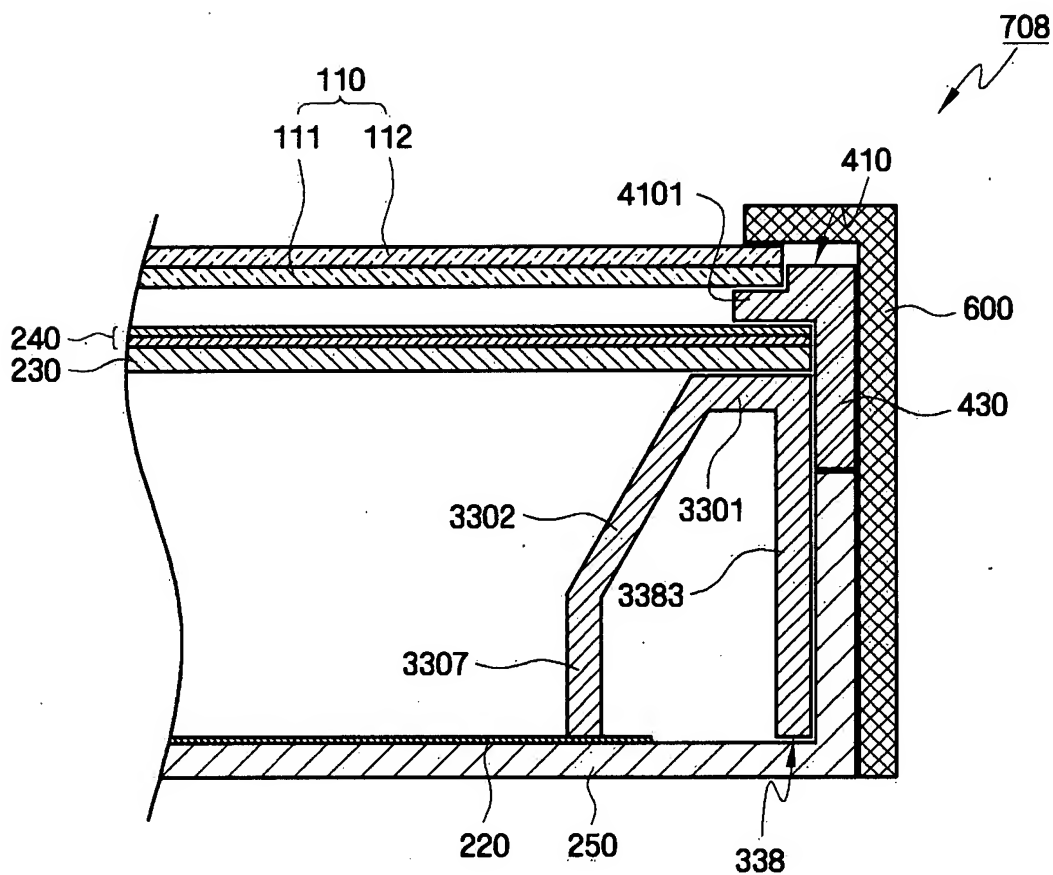


FIG. 14

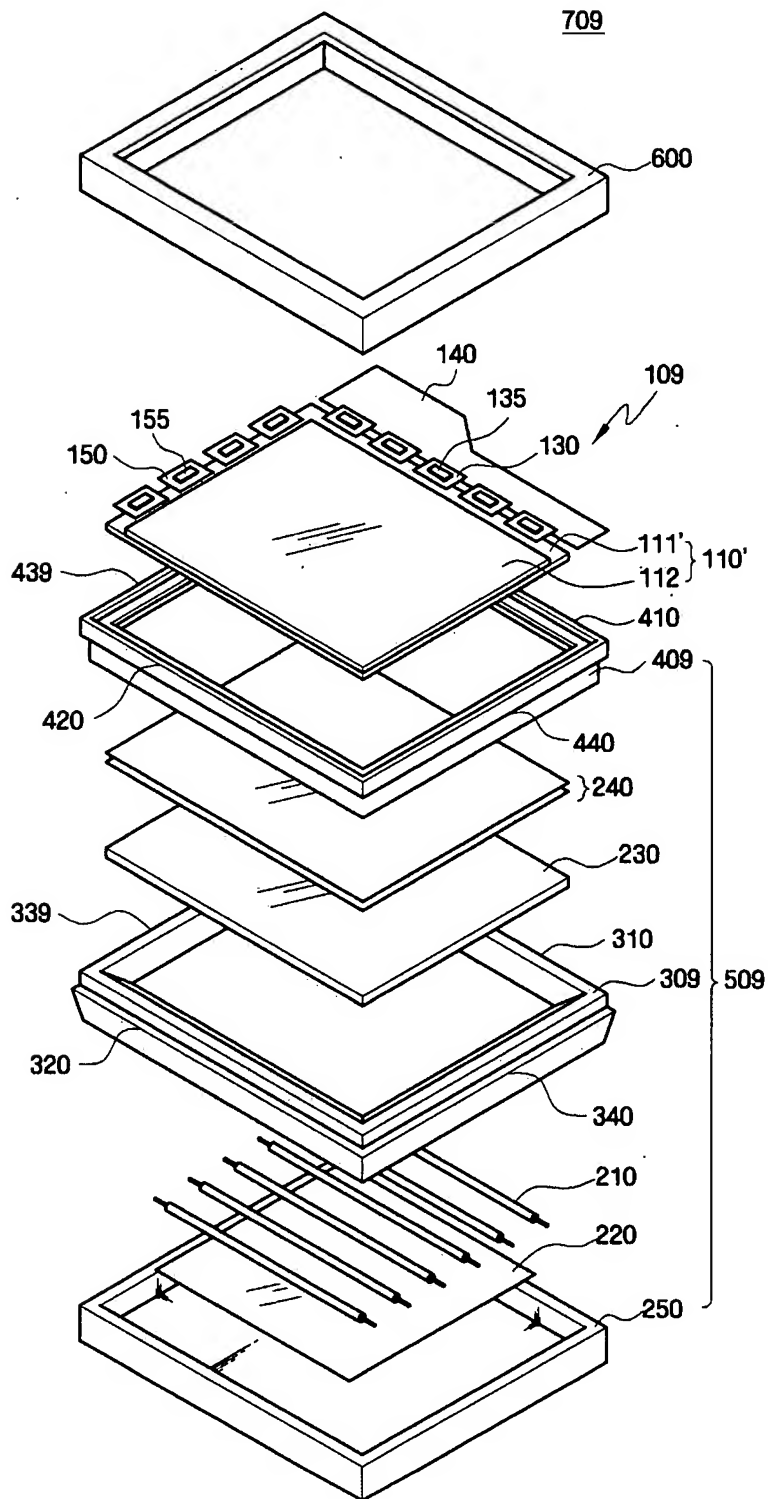


FIG. 15

